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(54) PROTRUDED ELECTRODE AND ITS MANUFACTURE

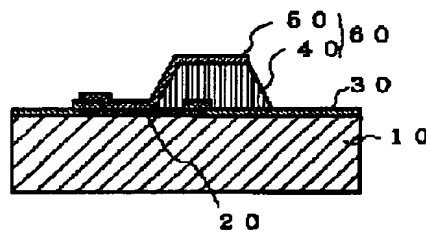
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(57) Abstract

PROBLEM TO BE SOLVED: To test a semiconductor device before and after a protruded electrode is formed without losing the degree of freedom in laying out the protruded electrode by providing an insulating resin so as to overlap with the electrode and a protective film and providing a metal film so as to cover the top of the electrode and the insulating resin in a predetermined layout.

SOLUTION: An insulating resin 40 is provided so as to overlap with an electrode 20 at a coverage of 5 to 60% of an opening of a protective film 30 that is formed on a semiconductor device 10, and a metal film 50 is provided so as to overlap with the resin 40 and the opening of the film 30. Therefore, the resin 40 is provided so as to overlap with the electrode 20 and the film 30, and the film 50 with the electrode 20 and the resin 40, and thus the film 50 is electrically connected to the electrode 20. The film 50 is provided on the resin 40 so as to cover at least the entire surface of the top of the resin 40, and on the electrode 20 at a size larger than the opening of the film 30 by 2 μm or



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